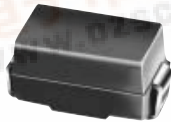




EGF1A thru EGF1D

Vishay General Semiconductor

Surface Mount Glass Passivated Ultrafast Rectifier



DO-214BA (GF1)

* Glass-plastic encapsulation technique is covered by patent No. 3,996,602, brazed-lead assembly by Patent No. 3,930,306 and lead forming by Patent No. 5,151,846

FEATURES

- Cavity-free glass-passivated junction
- Ideal for automated placement
- Ultrafast reverse recovery time
- Low switching losses, high efficiency
- High forward surge capability
- Meets environmental standard MIL-S-19500
- Meets MSL level 1, per J-STD-020, LF maximum peak of 250 °C
- Solder dip 260 °C, 40 s
- Component in accordance to RoHS 2002/95/EC and WEEE 2002/96/EC



RoHS COMPLIANT

TYPICAL APPLICATIONS

For use in high frequency rectification and freewheeling application in switching mode converters and inverters for consumer, computer, automotive and telecommunication.

MECHANICAL DATA

Case: DO-214BA, molded epoxy over glass body

Epoxy meets UL 94V-0 flammability rating

Terminals: Matte tin plated leads, solderable per J-STD-002 and JESD22-B102

E3 suffix for consumer grade, meets JESD 201 class 1A whisker test, HE3 suffix for high reliability grade (AEC Q101 qualified), meets JESD 201 class 2 whisker test

Polarity: Color band denotes cathode end

PRIMARY CHARACTERISTICS

$I_{F(AV)}$	1.0 A
V_{RRM}	50 V to 200 V
I_{FSM}	30 A
t_{rr}	50 ns
V_F	1.0 V
$T_J \text{ max.}$	175 °C

MAXIMUM RATINGS ($T_A = 25\text{ °C}$ unless otherwise noted)

PARAMETER	SYMBOL	EGF1A	EGF1B	EGF1C	EGF1D	UNIT
Device marking code		EA	EB	EC	ED	
Maximum repetitive peak reverse voltage	V_{RRM}	50	100	150	200	V
Maximum RMS voltage	V_{RMS}	35	70	105	140	V
Maximum DC blocking voltage	V_{DC}	50	100	150	200	V
Maximum average forward rectified current at $T_L = 125\text{ °C}$	$I_{F(AV)}$	1.0				A
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load	I_{FSM}	30				A
Operating junction and storage temperature range	T_J, T_{STG}	- 65 to + 175				°C



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ELECTRICAL CHARACTERISTICS (T _A = 25 °C unless otherwise noted)								
PARAMETER	TEST CONDITIONS		SYMBOL	EGF1A	EGF1B	EGF1C	EGF1D	UNIT
Maximum instantaneous forward voltage ⁽¹⁾	1.0 A		V _F	1.0				V
Maximum DC reverse current at rated DC blocking voltage ⁽¹⁾		T _A = 25 °C T _A = 125 °C	I _R	5.0 50				μA
Typical reverse recovery time	I _F = 0.5 A, I _R = 1.0 A, I _{rr} = 0.25 A		t _{rr}	50				ns
Typical junction capacitance	4.0 V, 1 MHz		C _J	15				pF

Note:

(1) Pulse test: 300 μs pulse width, 1 % duty cycle

THERMAL CHARACTERISTICS ($T_A = 25\text{ }^{\circ}\text{C}$ unless otherwise noted)							
PARAMETER	SYMBOL	EGF1A	EGF1B	EGF1C	EGF1D	UNIT	
Typical thermal resistance ⁽¹⁾	$R_{\theta JA}$ $R_{\theta JL}$	85 30				$^{\circ}\text{C/W}$	

Note:

(1) Thermal resistance from junction to ambient and from junction to lead, P.C.B. mounted on 0.2 x 0.2" (5.0 x 5.0 mm) copper pad areas

ORDERING INFORMATION (Example)				
PREFERRED P/N	UNIT WEIGHT (g)	PREFERRED PACKAGE CODE	BASE QUANTITY	DELIVERY MODE
EGF1D-E3/67A	0.104	67A	1500	7" diameter plastic tape and reel
EGF1D-E3/5CA	0.104	5CA	6500	13" diameter plastic tape and reel
EGF1DHE3/67A ⁽¹⁾	0.104	67A	1500	7" diameter plastic tape and reel
EGF1DHE3/5CA ⁽¹⁾	0.104	5CA	6500	13" diameter plastic tape and reel

Note:

(1) Automotive grade AEC Q101 qualified

RATINGS AND CHARACTERISTICS CURVES

($T_A = 25\text{ }^{\circ}\text{C}$ unless otherwise specified)

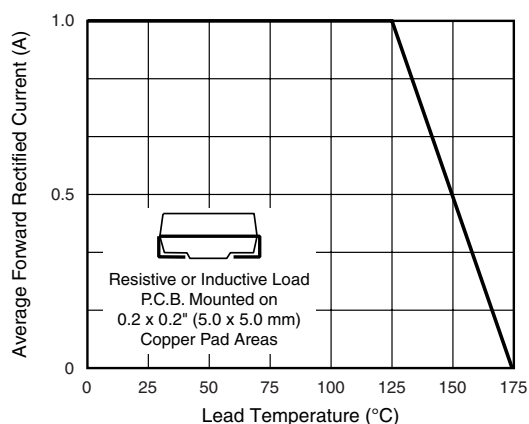


Figure 1. Maximum Forward Current Derating Curve

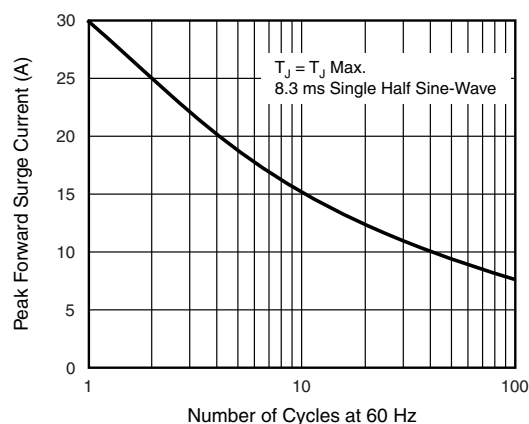


Figure 2. Maximum Non-Repetitive Peak Forward Surge Current



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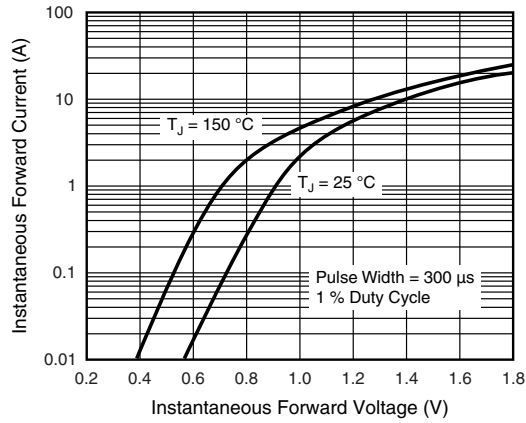


Figure 3. Typical Instantaneous Forward Characteristics

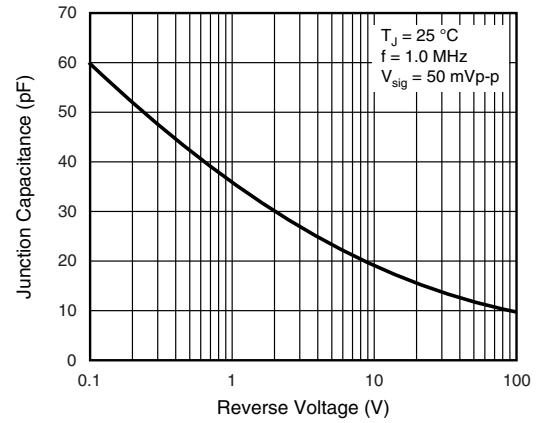


Figure 5. Typical Junction Capacitance

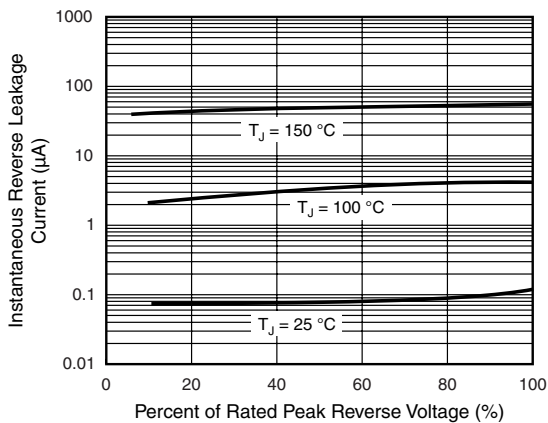


Figure 4. Typical Reverse Leakage Characteristics

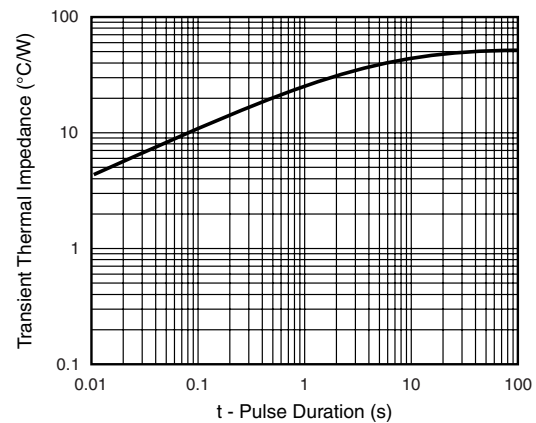
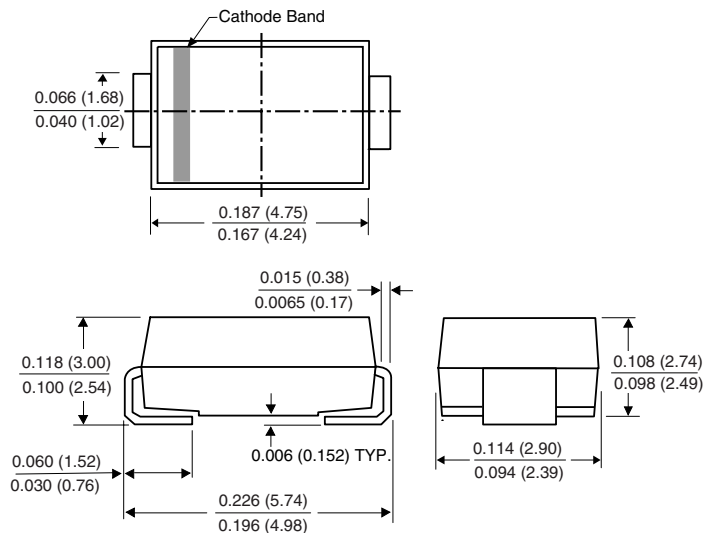


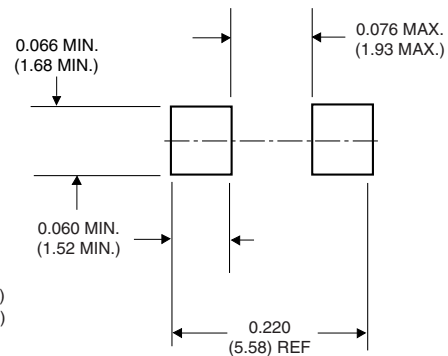
Figure 6. Typical Transient Thermal Impedance

PACKAGE OUTLINE DIMENSIONS in inches (millimeters)

DO-214BA (GF1)



Mounting Pad Layout





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